

67,200-409; TSMC 00-661
Serial Number 09/978,420

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

TO: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

FROM: Tung & Associates
838 West Long Lake Road - Suite 120
Bloomfield Hills, MI 48302

DATE: 7 July 2004

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REF: Applicant : Chou et al Filing Date : 15 October 2001
Serial No. : 09/978,420 Atty No. : 67,200-409; TSMC 00-661
Art Unit : 2815 Examiner : N. Drew Richards
Title : Microelectronic Fabrication With Upper Lying Aluminum Fuse
Layer in Copper Interconnect Semiconductor Technology and
Method for Fabrication Thereof

RESPONSE TO OFFICE ACTION MADE FINAL

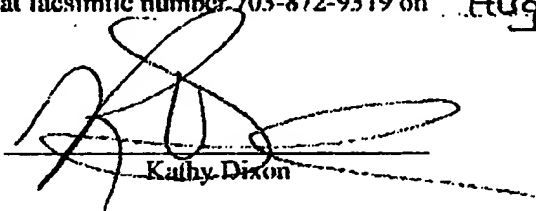
Sir:

In response to an office action mailed on 8 June 2004 and made FINAL, please consider the following remarks pertaining to the above referenced application.

There are no amendments to the specification, claims or drawings. A Listing of the Claims begins on page 2 of this paper. Remarks begin on page 4 of this paper.

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this correspondence is being facsimile transmitted to the United States Patent and Trademark Office at facsimile number 703-872-9319 on Aug. 9, 2004.


Kathy Dixon